

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Katsuhisa ITO</td> <td>04/13/2011</td> </tr> <tr> <td>Naoya EGUCHI</td> <td>04/14/2011</td> </tr> <tr> <td>Hiroki KIKUCHI</td> <td>04/14/2011</td> </tr> <tr> <td>Shinichiro TAJIRI</td> <td>04/14/2011</td> </tr> <tr> <td>Izushi KOBAYASHI</td> <td>04/15/2011</td> </tr> <tr> <td>Hiroaki YASUNAGA</td> <td>04/14/2011</td> </tr> </tbody> </table>		Name	Execution Date	Katsuhisa ITO	04/13/2011	Naoya EGUCHI	04/14/2011	Hiroki KIKUCHI	04/14/2011	Shinichiro TAJIRI	04/14/2011	Izushi KOBAYASHI	04/15/2011	Hiroaki YASUNAGA	04/14/2011
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CORRESPONDENCE DATA															
<p>Fax Number: (312)441-0570 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 312.277.2006 Email: dayala@rdlklaw.com</p> <p>Correspondent Name: ROBERT J. DEPKE Address Line 1: ROCKEY, DEPKE & LYONS, LLC Address Line 2: SUITE 5450 SEARS TOWER Address Line 4: CHICAGO, ILLINOIS 60606-6306</p>															
ATTORNEY DOCKET NUMBER:	075834.01307														

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PATENT
REEL: 026348 FRAME: 0879

CH \$40.00 13131507

NAME OF SUBMITTER:

Robert J. Depke

Total Attachments: 2

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509 P2070

Docket Number: 075834-01307

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

3D IMAGE DISPLAY DEVICE, METHOD FOR MANUFACTURING SAME, AND 3D IMAGE DISPLAY METHOD

for which an application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, the entire right, title and interest in the said invention, said application, including any divisions and continuations as well as any reissues and reexaminations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

PCT Application No. PCT/JP2009/070672

PCT Filing Date: December 10, 2009

This assignment executed on the dates indicated below.

Katsuhisa ITO

Name of first or sole inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of first or sole inventor

Katsuhisa Ito
Signature of first or sole inventor

April 13, 2011

Date of this Assignment

PATENT

REEL: 026348 FRAME: 0881

Naoya EGUCHI

Name of second inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of second inventor

Naoya Eguchi
Signature of second inventor

April 14, 2011
Date of this Assignment

Hiroki KIKUCHI

Name of third inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of third inventor

Hiroki Kikuchi
Signature of third inventor

April 14, 2011
Date of this Assignment

Shinichiro TAJIRI

Name of fourth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of fourth inventor

Shinichiro Tajiri
Signature of fourth inventor

April 14, 2011
Date of this Assignment

Izushi KOBAYASHI

Name of fifth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of fifth inventor

Izushi Kobayashi
Signature of fifth inventor

April 15, 2011
Date of this Assignment

Hiroaki YASUNAGA

Name of sixth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of sixth inventor

Hiroaki Yasunaga
Signature of sixth inventor

April 14, 2011
Date of this Assignment

Name of seventh inventor

Execution date of U.S. Patent Application

Residence of seventh inventor

Signature of seventh inventor

Date of this Assignment